

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	602726	(stack stacking stacked stackable mount mounting mounted) with (chip die ic (integrated adj circuit) microelectronic component semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 11:25
L2	192590	(substrate board pcb ((wiring printed circuit) adj4 board)) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 11:26
L3	4827	(encapsulated encapsulating encapsulated encase) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/08 11:27